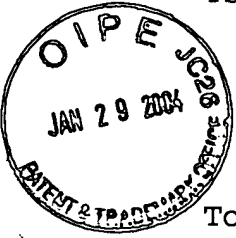


TSMC-03-336

January 22, 2004



To: Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/718,192 11/20/03 |
Yian-Liang Kuo et al.
A HEAT SPREADER BALL GRID ARRAY
(HSBGA) DESIGN FOR LOW-K INTEGRATED
CIRCUITS (IC)
| _____ |

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on January 27, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 1/27/04

U.S. Patent 5,977,633 to Suzuki et al., "Semiconductor Device with Metal Base Substrate Having Hollows," describes a semiconductor device with metal base substrate having hollows.

U.S. Patent 5,223,741 to Bechtel et al., "Package for an Integrated Circuit Structure," describes a package for an integrated circuit structure.

U.S. Patent 5,585,671 to Nagesh et al., "Reliable Low Thermal Resistance Package for High Power Flip Chip ICs," describes a low thermal resistance package for high power flip chip ICs.

U.S. Patent 6,462,410 to Novotny et al., "Integrated Circuit Component Temperature Gradient Reducer," describes an integrated circuit component temperature gradient reducer.

U.S. Patent 4,748,495 to Kucharek, "High Density Multi-Chip Interconnection and Cooling Package," describes a high density multi-chip interconnection and cooling package.

Sincerely,

A handwritten signature in black ink, appearing to be 'SBA', written over a horizontal line.

Stephen B. Ackerman,
Reg. No. 37761

Form PTO-1449

Sheet 1 of 1

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

Document Number (Optional)

TSMC-03-336

Application Number

10/718,192

Applicant

Yian-Liang Kao et al.

Filing Date

11/20/03

Group Art Unit

U. S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	5977633	11/2/99	Suzuki et al.	257	738	5/29/98
	5223741	6/29/93	Bechtel et al.	257	678	9/1/89
	5585671	12/17/96	Nagesh et al.	257	697	10/7/94
	6462410	10/8/02	Novotny et al.	257	707	8/17/00
	4748495	5/31/88	Kucharek	357	82	8/8/85

FOREIGN PATENT DOCUMENTS

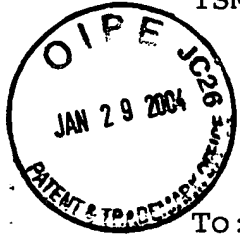
DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
					YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.



January 22, 2004

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| _____ |

ASSOCIATE POWER OF ATTORNEY

I hereby appoint Stephen G. Stanton, registration number 35,690, as my associate attorney in this case. His telephone number is (610) 296-5194.

Please continue to direct all correspondence in this case to the undersigned attorney.

Respectfully submitted,

Stephen B. Ackerman,

Principal attorney of record